

Title (en)
Method for manufacturing a honeycomb structure

Title (de)
Verfahren zur Herstellung einer Wabenstruktur

Title (fr)
Procédé de fabrication d'une structure en nid d'abeille

Publication
EP 2138290 A3 20120523 (EN)

Application
EP 09251553 A 20090612

Priority
JP 2008165597 A 20080625

Abstract (en)
[origin: EP2138290A2] A method for manufacturing a honeycomb structure 130 includes: subjecting a forming raw material to extrusion forming to obtain a segment-joined type honeycomb formed article 100 provided with honeycomb segments 1 and an outer peripheral portion 2 surrounding a whole outermost periphery of the honeycomb segments, wherein a slit-shaped gap 8 extending from one end face 11 to the other end face 12 is formed between adjacent segments, the adjacent honeycomb segments are joined by a belt-like joining rib 4 extending from the face 11 to the face 12 and having a thickness of 0.1 to 1.5 mm, and the honeycomb segments 1 have partition walls separating and forming cells; firing the honeycomb formed article 100 to form a honeycomb fired article 110; destroying the joining rib 4 in the honeycomb fired article 110; and forming a buffer portion 7 by filling a bonding material in the gap 3.

IPC 8 full level
B28B 3/20 (2006.01); **B28B 11/00** (2006.01)

CPC (source: EP US)
B28B 3/269 (2013.01 - EP US); **B28B 11/003** (2013.01 - EP US); **B28B 11/006** (2013.01 - EP US)

Citation (search report)
• [E] EP 2151553 A1 20100210 - NGK INSULATORS LTD [JP]
• [AP] EP 1964655 A1 20080903 - IBIDEN CO LTD [JP]
• [A] US 2006292331 A1 20061228 - OHNO KAZUSHIGA [JP], et al

Cited by
EP2105274A3; US8257629B2

Designated contracting state (EPC)
AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO SE SI SK TR

Designated extension state (EPC)
AL BA RS

DOCDB simple family (publication)
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